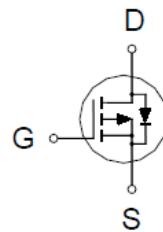


P1203EEA

P-Channel Logic Level Enhancement Mode MOSFET

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
-30V	12mΩ @ $V_{GS} = -10V$	-40A



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNITS
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 25	
Continuous Drain Current ²	I_D	-40	A
		-25	
		-11	
		-9	
		-95	
Pulsed Drain Current ¹	I_{DM}	-95	mJ
Avalanche Current	I_{AS}	45	
Avalanche Energy	E_{AS}	101	
Power Dissipation	P_D	31	W
		12	
		2.2	
		1.4	
Operating Junction & Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

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THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE		SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient ³	Steady-State	R _{θJA}		55	
Junction-to-Ambient	Steady-State	R _{θJC}		4	°C / W

¹Pulse width limited by maximum junction temperature.

²Package limitation current is -30A.

³The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A = 25°C. The value in any given application depends on the user's specific board design.

ELECTRICAL CHARACTERISTICS (T_J = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-30			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-1	-1.5	-2.5	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0V, V _{GS} = ±25V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -24V, V _{GS} = 0V			-1	μA
		V _{DS} = -20V, V _{GS} = 0V, T _J = 125 °C			-10	
On-State Drain Current ¹	I _{D(ON)}	V _{DS} = -5V, V _{GS} = -10V	-95			A
Drain-Source On-State Resistance ¹	R _{DS(ON)}	V _{GS} = -4.5V, I _D = -9A		13	19	mΩ
		V _{GS} = -10V, I _D = -12A		8.8	12	
Forward Transconductance ¹	g _f	V _{DS} = -5V, I _D = -12A		31		S
DYNAMIC						
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = -15V, f = 1MHz		2760		pF
Output Capacitance	C _{oss}			437		
Reverse Transfer Capacitance	C _{rss}			395		
Gate Resistance	R _g	V _{GS} = 0V, V _{DS} = 0V, f = 1MHz		2.5		Ω
Total Gate Charge ²	Q _g (V _{GS} =-10V)	V _{DS} = -15V, I _D = -12A		64		nC
	Q _g (V _{GS} =-4.5V)			33		
Gate-Source Charge ²	Q _{gs}			10		
Gate-Drain Charge ²	Q _{gd}			16		
Turn-On Delay Time ²	t _{d(on)}	V _{DS} = -15V, I _D ≈ -12A, V _{GS} = -10V, R _{GS} = 6Ω		21		nS
Rise Time ²	t _r			25		
Turn-Off Delay Time ²	t _{d(off)}			100		
Fall Time ²	t _f			73		

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SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ\text{C}$)						
Continuous Current ³	I_S				-40	A
Forward Voltage ¹	V_{SD}	$I_F = -12\text{A}, V_{GS} = 0\text{V}$			-1.2	V
Reverse Recovery Time	t_{rr}	$I_F = -12\text{A}, dI_F/dt = 100\text{A} / \mu\text{s}$	21			nS
Reverse Recovery Charge	Q_{rr}		7			nC

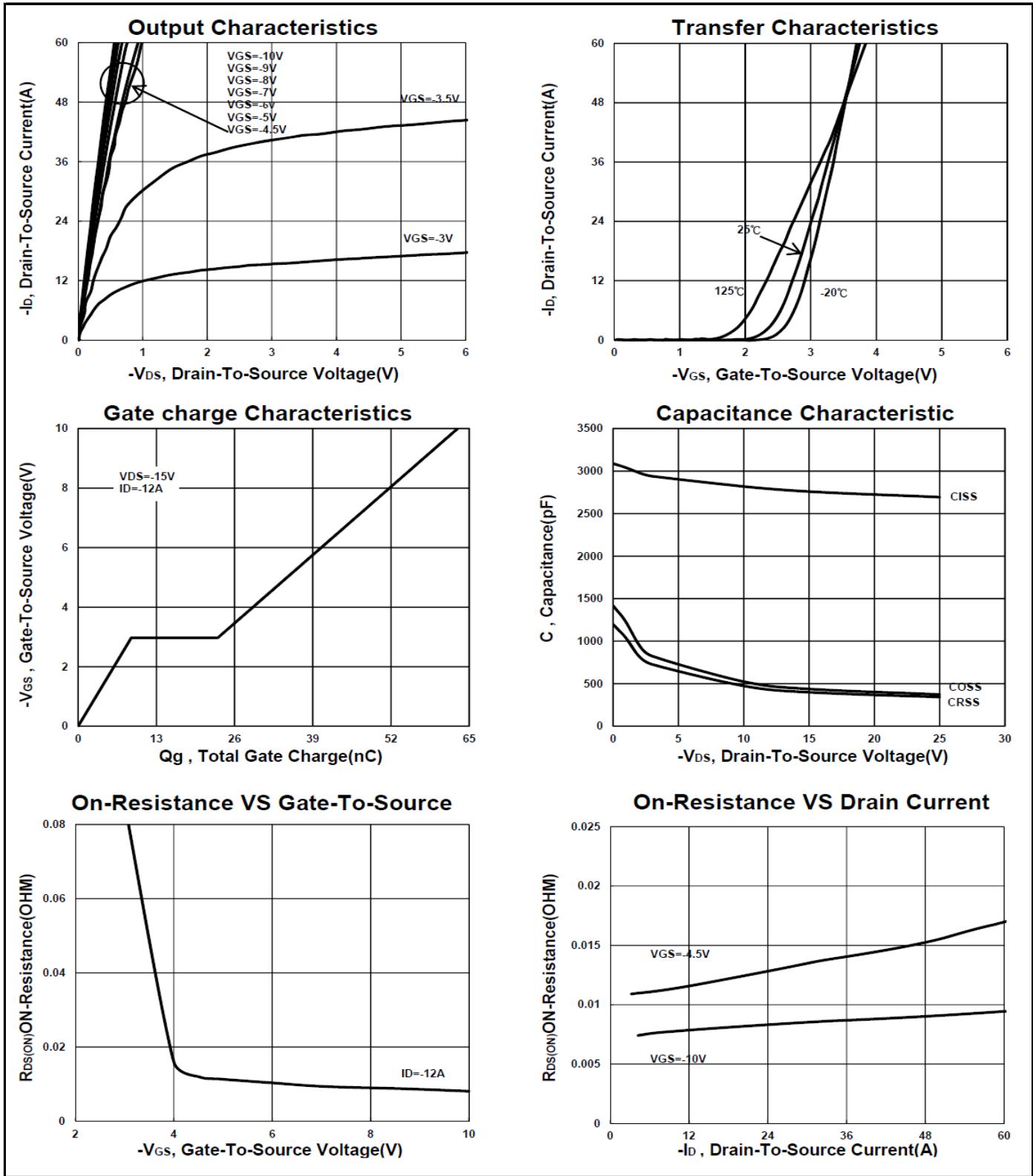
¹Pulse test : Pulse Width $\leq 300 \mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

³Package limitation current is -30A.

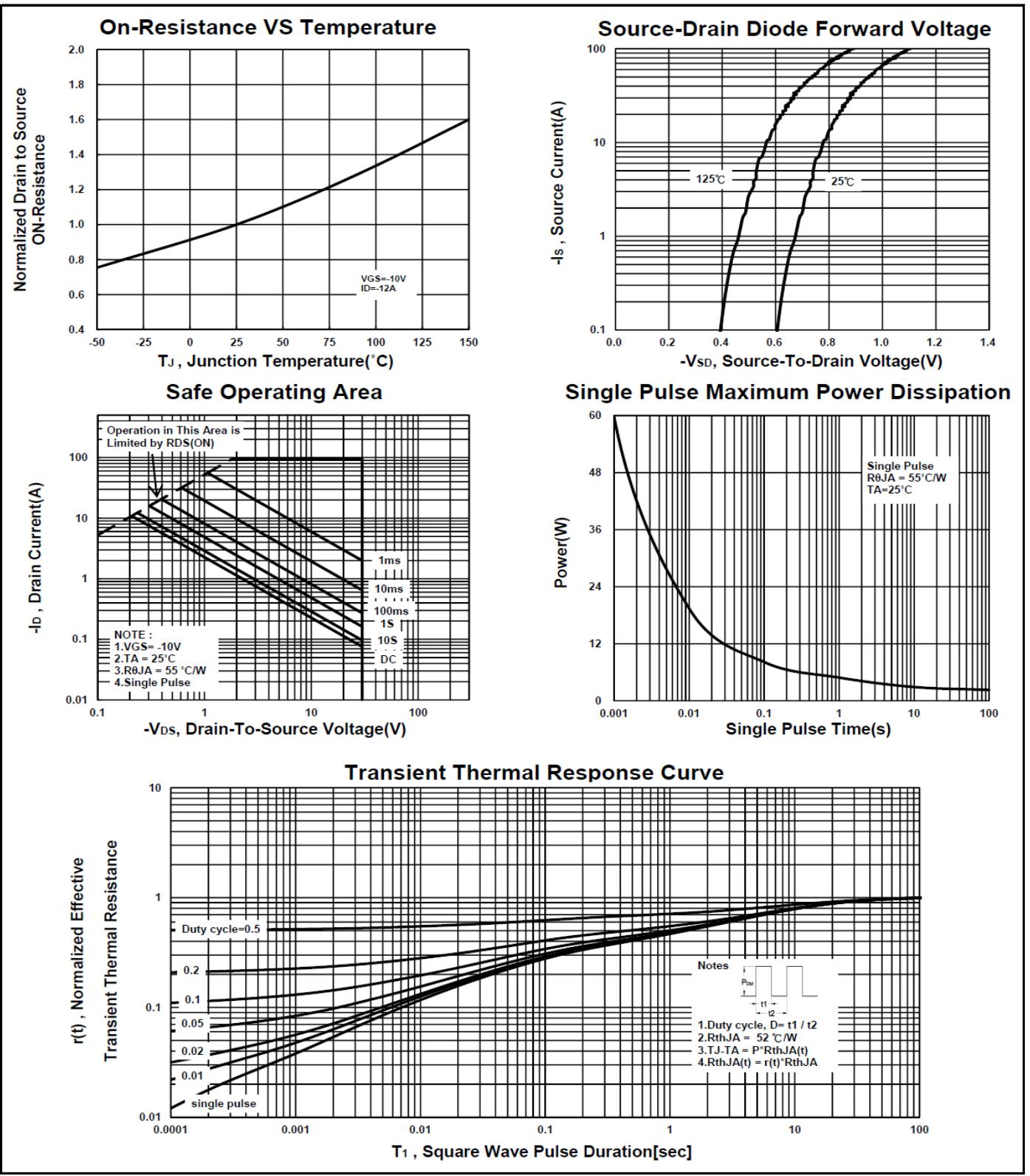
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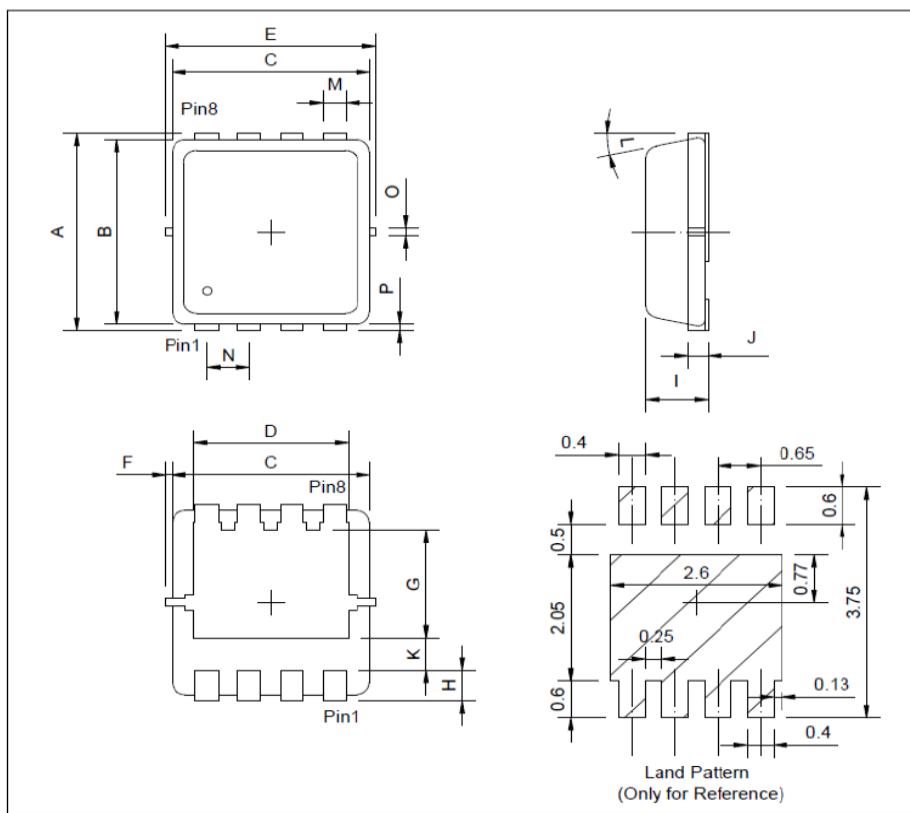
P1203EEA

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Package Dimension

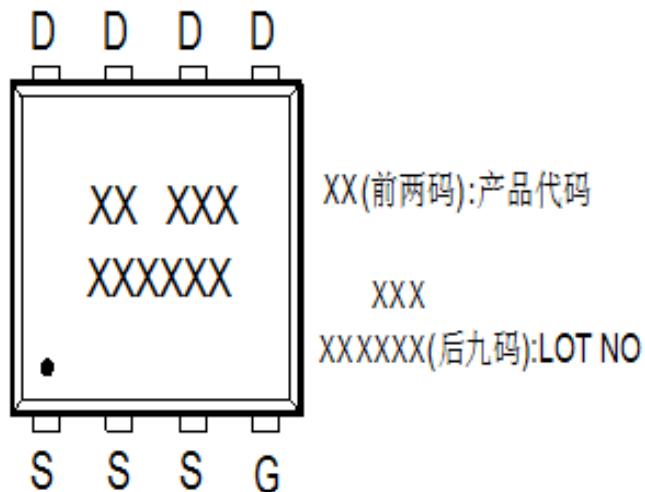
PDFN 3x3P MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	3	3.3	3.6	I	0.65	0.8	0.9
B	2.88	3	3.2	J	0.1	0.15	0.25
C	2.9	3	3.25	K	0.59		
D	2.29	2.45	2.69	L	0°	10°	12°
E	3	3.3	3.6	M	0.14	0.3	0.4
F	0	0.1	0.2	N	0.55	0.65	0.75
G	1.35	1.75	2.2	O		0.2	
H	0.15	0.3	0.55	P	0		0.2

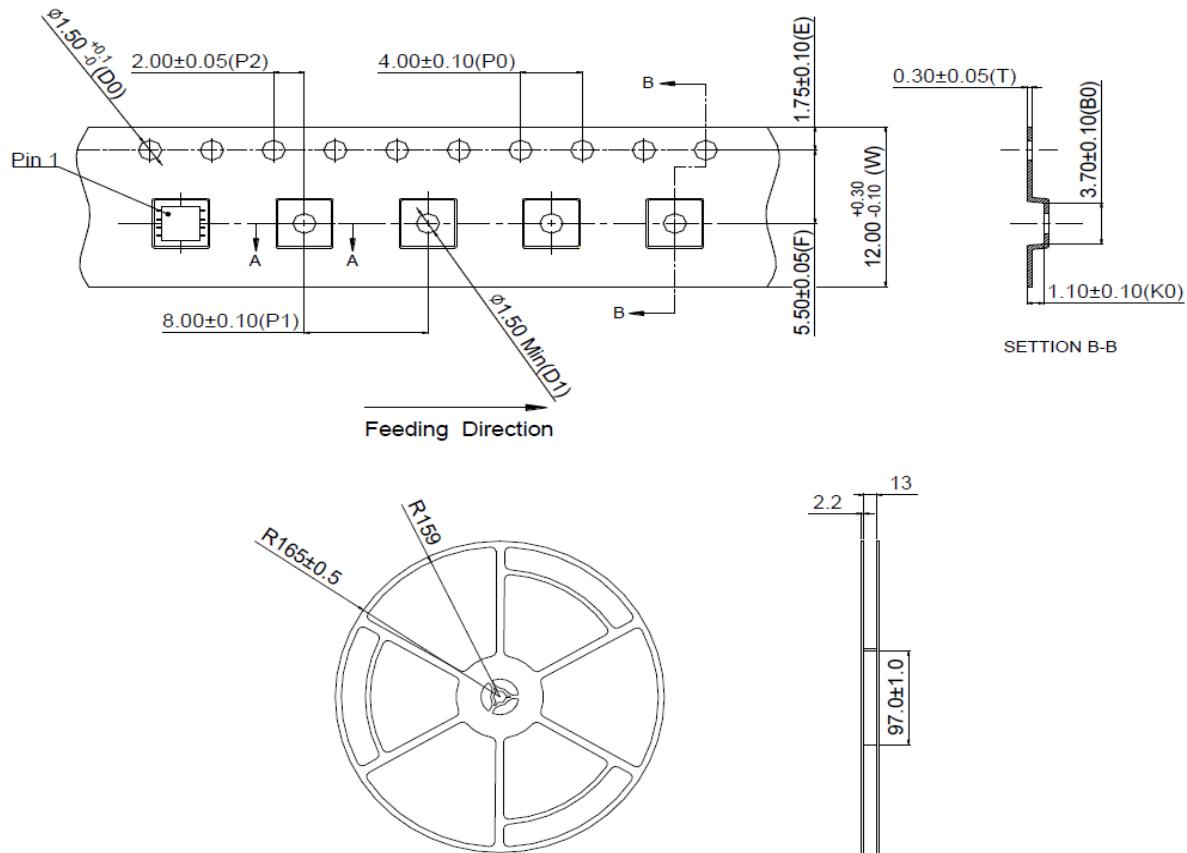


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A. Marking Information(此产品代码为: B2)



B. Tape&Reel Information:5000pcs/Reel



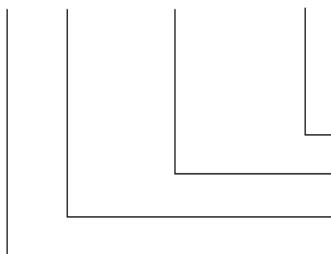
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C. Lot.No. & Date Code rule

1.LOT.NO.

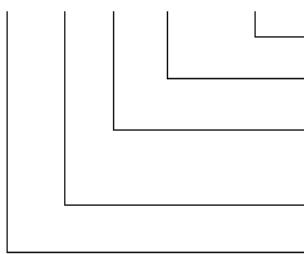
M N 15M21 03



- #8~9 Sub-lot No
- Order series no.
- Foundry site
- Assembly site

2.Date Code

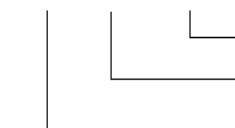
D Y M X XXX



- Order series no. & Sub-lot No
- Week
- M : Month (A:Jan , B:Feb , C:Mar ,D :Apr ,E:May ,F:Jun,G:Jul,H:Aug,I:Sep,J:Oct,K:Nov,L:Dec.)
- Y : Year (N : 2011, O : 2012 ...)
- Assembly site

3.Date Code (for Small package)

XX Y WW



- Week
- Y : Year (9: 2009,A : 2010, B : 2011 ...)
- Device Name

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D.Label rule

标签内容(Label content)



1	Label Size	30 * 90 mm
2	Font style	Times New Roman or Arial (或可区分英文“0”和数字“0”，“G”和“Q”的字型即可)
3	Great Power	Height: 4 mm
4	Package	Height: 2 mm
5	Date	Height: 2 mm Shipping date: YYYY/MM/DD, ex. 2008/09/12
6	Device	Height: 3 mm (Max: 16 Digit)
7	Lot	Height: 3 mm (Max: 9 Digit) Sub lot
8	D/C	Height: 3 mm (Max: 7 Digit)
9	QTY	Height: 3 mm (Max: 6 Digit) Thousand mark is no needed
10	Pb Free label	 Diameter: 1 cm bottom color: Green Font color: Black Font style: Arial
11	Halogen Free label	 Diameter: 1 cm bottom color: Green Font color: Black Font style: Arial
12	Scan info	Device / Lot / D/C / QTY , Insert “/” between every parts. for example: P3055LDG/G12345601/GGG2301/2000 DPI (Dots per inch): Over 300 dpi Code : Code 128 Height: 6 mm at least